

Bill of Materials

TI DESIGNS

TIDA-00513

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	!PCB		Printed Circuit Board	Any	TIDA-00513	
2	4	C21, C27, C31, C35	1uF	CAP, CERM, 1 μ F, 16 V, +/- 10%, X5R, 0603	TDK	C1608X5R1C105K	0603
3	4	C23, C24, C33, C34	0.01uF	CAP, CERM, 0.01 μ F, 50 V, +/- 5%, X7R, 0603	Kemet	C0603C103J5RACTU	0603
4	1	C25	220pF	CAP, CERM, 220 pF, 50 V, +/- 5%, COG/NPO, 0603	Kemet	C0603C221J5GACTU	0603
5	3	C28, C32, C36	10uF	CAP, CERM, 10 μ F, 16 V, +/- 10%, X6S, 0805	TDK	C2012X6S1C106MT	0805
6	4	H9, H10, H11, H12		Bumpon, Hemisphere, 0.44 X 0.20, Clear	3M	SJ-5303 (CLEAR)	Transparent Bumpon
7	2	J21, J22		TERMINAL BLOCK 5.08MM VERT 2POS, TH	On-Shore Technology	ED120/2DS	TERM_BLK, 2pos, 5.08mm
8	2	J31, J32		Terminal Block, 30A, 9.52mm (.375) Pitch, 2-Pos, TH	On-Shore Technology	OSTT7022150	19.62x21.5x12.5mm
9	2	JP21, JP32		Header, 100mil, 3x1, Gold, TH	Samtec	TSW-103-07-G-S	3x1 Header
10	2	JP22, JP31		Header, 100mil, 2x1, Gold, TH	Samtec	HMTSW-102-07-G-S-240	Header, 2.54mm, 2x1, TH
11	4	SH-JP21, SH-JP22, SH-JP31,	1x2	Shunt, 100mil, Gold plated, Black	3M	969102-0000-DA	Shunt
12	9	TP21, TP23, TP24, TP25, TP22, TP27, TP28, TP29,	Red	Test Point, Compact, Red, TH	Keystone	5005	Red Compact Testpoint
13	8	TP32, TP36, TP37, TP38	Black	Test Point, Miniature, Black, TH	Keystone	5001	Black Miniature Testpoint
14	1	U21		ULTRA-LOW ON-RESISTANCE, 6-A DUAL LOAD SWITCH WITH CONTROLLED TURN-ON, DPU0014A	Texas Instruments	TPS22966DPU	DPU0014A
15	3	U31, U32, U33		ULTRA-LOW RESISTANCE LOAD SWITCH, DNY0008A	Texas Instruments	TPS22959DNY	DNY0008A
16	0	C22, C37	10uF	CAP, CERM, 10 μ F, 16 V, +/- 10%, X6S, 0805	TDK	C2012X6S1C106MT	0805
17	0	C26	220pF	CAP, CERM, 220 pF, 50 V, +/- 5%, COG/NPO, 0603	Kemet	C0603C221J5GACTU	0603
18	0	C29, C38	47uF	CAP, CERM, 47 μ F, 16 V, +/- 15%, X5R, 1206	TDK	C3216X5R1C476M160AB	1206
19	0	FID1, FID2, FID3		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	Fiducial

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